



**PATENT**  
Attorney Docket No. 98124X205843

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

Wang et al.

Application No. 09/636,246

Art Unit: 1765

Examiner: Charlotte A. Brown

Filed: August 10, 2000

For: POLISHING SYSTEM WITH  
STOPPING COMPOUND AND  
METHOD OF ITS USE

**AMENDMENTS TO CLAIMS  
MADE IN RESPONSE TO OFFICE ACTION DATED MAY 31, 2002**

*Amendments to existing claims:*

- 32. cancelled
- 33. cancelled
- 34. cancelled
- 35. cancelled
- 45. cancelled
- 46. cancelled

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PENDING CLAIMS AFTER AMENDMENTS  
MADE IN RESPONSE TO OFFICE ACTION DATED MAY 31, 2002

1. A system for polishing one or more layers of a multi-layer substrate that includes a first metal layer and a second layer comprising (i) a liquid carrier, (ii) at least one oxidizing agent, (iii) at least one polishing additive that increases the rate at which the system polishes at least one layer of the substrate, (iv) at least one stopping compound with a polishing selectivity of the first metal layer:second layer of at least about 30:1, wherein the stopping compound is a cationically charged nitrogen containing compound selected from compounds comprising amines, imines, amides, imides, and mixtures thereof, and (v) a polishing pad and/or an abrasive.
2. The system of claim 1, wherein the liquid carrier is a nonaqueous solvent.
3. The system of claim 1, wherein the liquid carrier is water.
4. The system of claim 3, wherein the system comprises an abrasive suspended in the liquid carrier.
5. The system of claim 3, wherein the abrasive is fixed on the polishing pad.
6. The system of claim 3, wherein no abrasive is present in the system, and the polishing pad is a non-abrasive pad.